2SK2342

Silicon N-Channel MOS

For motor drive For DC-DC converter

■ Features

- Low ON-resistance R_{DS(on)}
- High-speed switching

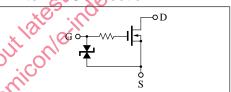
■ Absolute Maximum Ratings (Tc = 25°C)

Parameter	Symbol	Rating	Unit		
Drain-Source breakdown voltage	V _{DSS}	30	V		
Gate-Source voltage	V _{GSS}	±15	V		
Danier account	I_D	±2	A		
Drain current	I _{DP} *1	±8	A		
411 11 11 11	PD	0.75	W		
Allowable power dissipation	P _D *2	10	W		
Channel temperature	Tch	150	°C		
Storage temperature	T _{stg}	-55 to +150	°C		

^{* 1} $t \le 200\mu$ s, Duty Cycle < 10% *2 $T_C = 25^{\circ}$ C

Unit : mm 6.5±0.1 5.3±0.1 4.35±0.1 3.0±0.1 1.0±0.1 0.85±0.1 0.75±0.1 0.05 to 0.15 1 : Gate 2 : Drain 3 : Source EIAJ : SC-63 U Type Package

■ Internal Connection



■ Electrical Characteristics (Tc = 25°C

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Drain-Source cut-off current	I _{DSS}	$V_{DS} = 25V, V_{GS} = 0$			10	μΑ
Gate-Source leakage current	I _{GSS}	$V_{GS} = \pm 15V, V_{DS} = 0$			±10	μΑ
Drain-Source breakdown voltage	$V_{\rm DSS}$	$I_{D} = 0.1 \text{mA}, V_{GS} = 0$	30			V
Gate threshold voltage	V _{th}	V _{DS} =5V, I _D =1mA	0.8		2	V
Drain-Source ON-resistance	R _{DS(on)} Y	V ₆₈ = 4V, I _D =1A		0.32	0.45	Ω
	R _{DS(on)} 2	V_{GS} =10V, I_D =1A		0.26	0.35	Ω
Forward transadmittance	Y _{fs}	$V_{DS}=10V$, $I_D=1A$	1			S
Input capacitance	C _{iss}	V _{DS} =10V, V _{GS} = 0, f=1MHz		185		pF
Output capacitance	Coss			90		pF
Feedback capacitance	C _{rss}			35		pF
Turn-on time	t _{on}	V_{GS} =10V, I_D =1A, V_{DD} =10V R_L =10 Ω		40		ns
Fall time	t_{f}			100		ns
Turn-off time (delay time)	t _{d(off)}			180		ns

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